

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739444003

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, Guide Post Location A, Polarizing Key Position B, 72 Circuits

Documents:

3D Model

Packaging Specification PK-70873-0818 (PDF)

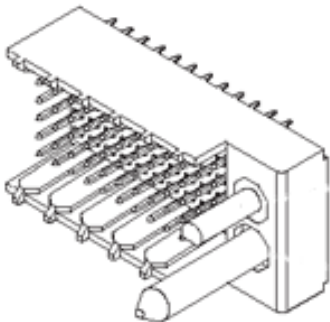
Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Product Specification PS-73670-9999 (PDF)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73944
Application	Backplane
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800755950984
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.00mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole

Electrical



Series image - Reference only

EU ELV	
Not Reviewed	
EU RoHS	China RoHS
Not Reviewed	
REACH SVHC	
Not Reviewed	
Halogen-Free	
Status	
Not Reviewed	
For more information, please visit Contact US	
China ROHS	Not Reviewed
ELV	Not Reviewed
RoHS Phthalates	Not Reviewed

Search Parts in this Series

73944 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

This document was generated on 09/12/2019

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Molex:

73944-4003